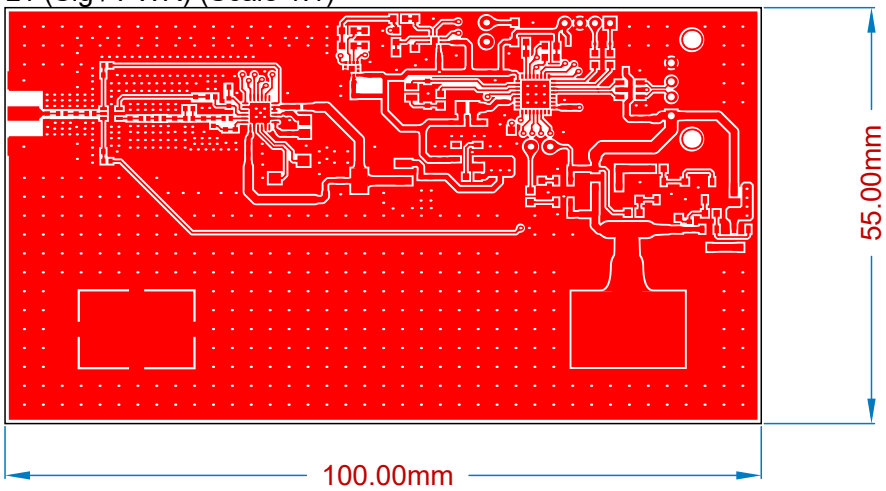
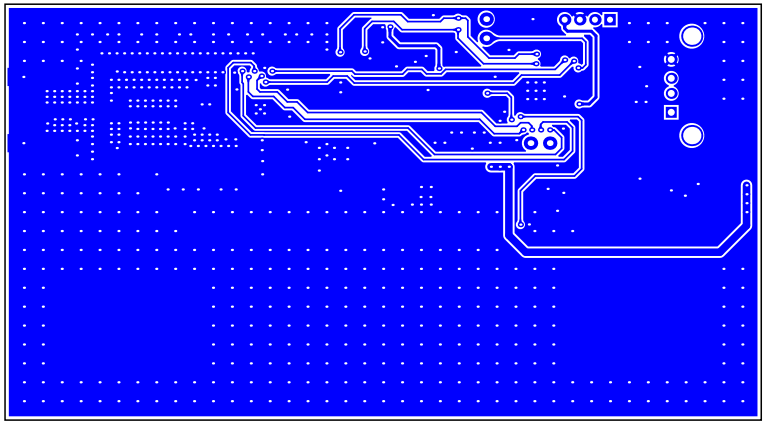
Widok warstw oraz wymiary PCB

L1 (Sig / PWR) (Scale 1:1)



L4 (Sig / PWR) (Scale 1:1)



Autor:	Ernest Rychlicki
Numer projektu:	LoRaIoT
Wykonanie:	V1
Data:	13.12.2023

Uproszczony BOM

Bill Of Materials

Line #	Designator	Comment	Quantity
1	C300, C400, C409, C412, C502, C505, C507, C510	1u	8
2	C301, C304, C305, C317, C401, C402, C406, C407, C413, C503, C504, C506, C508, C509, C600, C601, C602, C604	100n	18
3	C302, C314	470n	2
4	C303	47p	1
5	C306, C312, C313, C404, C405	3p3	5
6	C307, C308	39p	2
7	C309, C310	5p6	2
8	C311	2p2	1
9	C315, C316	2p4	2
10	C318	1p8	1
11	C403	100n	1
12	C408, C500, C501, C603	10u	4
13	C410, C411	47n	2
14	D500, D501, D502	B130LAW-7-F	3
15	J400	USB A	1
16	J401	ZL303-04P	1
17	L300, L301	47n	2
18	L302	2n5	1
19	L303	4n7	1
20	L304	9n1	1
21	L305, L400	15u	2
22	L306	15n	1
23	LED400, LED500	WP7113ID	2
24	Q500, Q503	BC850C	2
25	Q501, Q502	MMFTP3334K-AQ	2
26	R300, R302	10k	2
27	R301	0R	1
28	R400, R401, R402, R501, R503, R506	4k7	6
29	R404	10M	1
30	R405, R502	10k	2

Bill Of Materials

Line #	Designator	Comment	Quantity
31	R406, R407, R600, R601, R605	22R	5
32	R500, R504, R505, R507, R508	100k	5
33	SMA300	142-0701-841	1
34	TVS400, TVS401, TVS402	ESD9B3.3ST5G	3
35	U300	LLCC68IMLTRT	1
36	U301	4259-63	1
37	U400	STM32L052K8U6TR	1
38	U401	USBLC6-2SC6Y	1
39	U500	MCP73832T-2ACI/OT	1
40	U501	TLV1117LV33DCYR	1
41	U502	MIC5504-3.3YM5-TR	1
42	U600	BMP390	1
43	U601	LIS2DW12	1
44	Y300	32MHz	1
45	Y400	32.768kHz	1

Autor: Ernest Rychlicki

Numer projektu: LoRaIoT.P

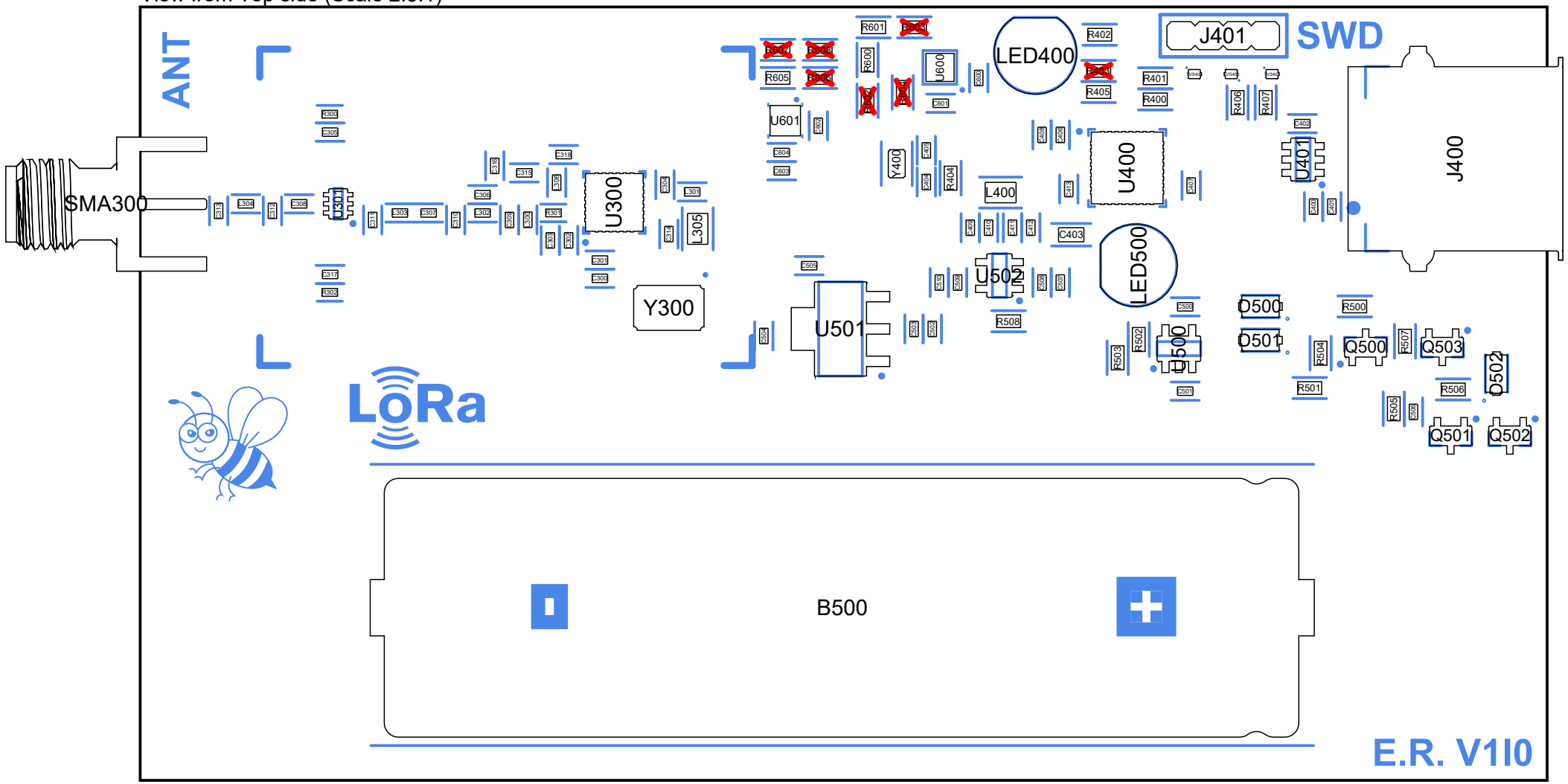
Wykonanie: V1

Data: 13.12.2023

Desygnatory TOP

Przekreślone elementy są nie montowane

View from Top side (Scale 2.5:1)



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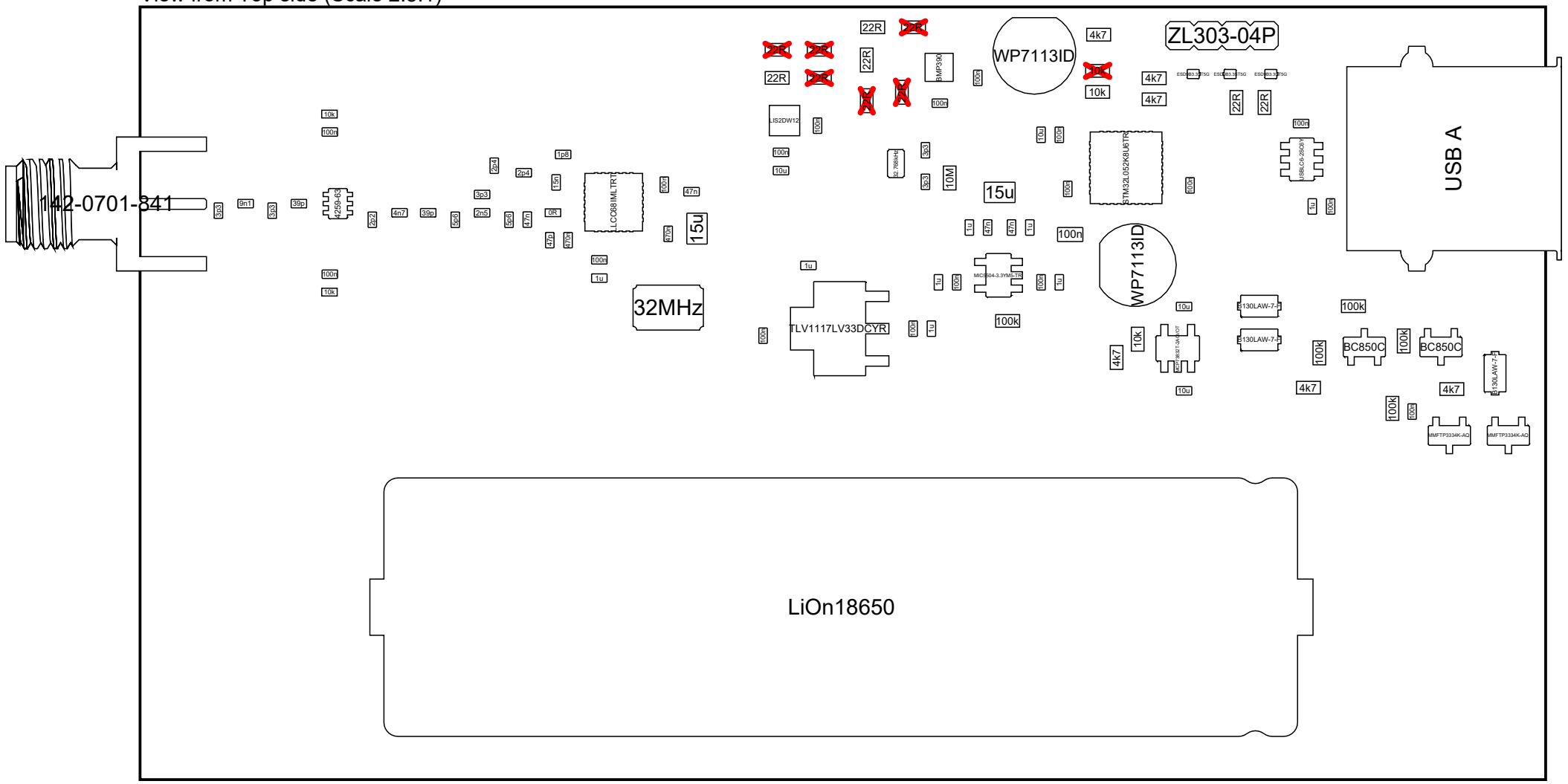
Wartości TOP

Przekreślone elementy są nie montowane

View from Top side (Scale 2.5:1)



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Wykonanie:	V1
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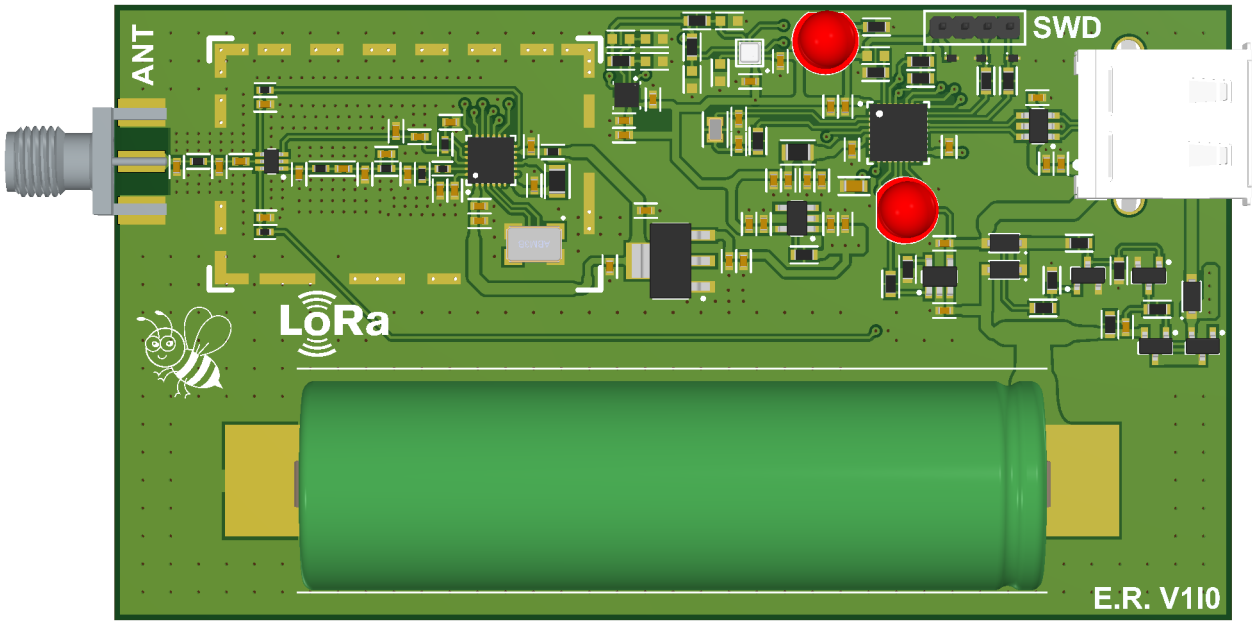
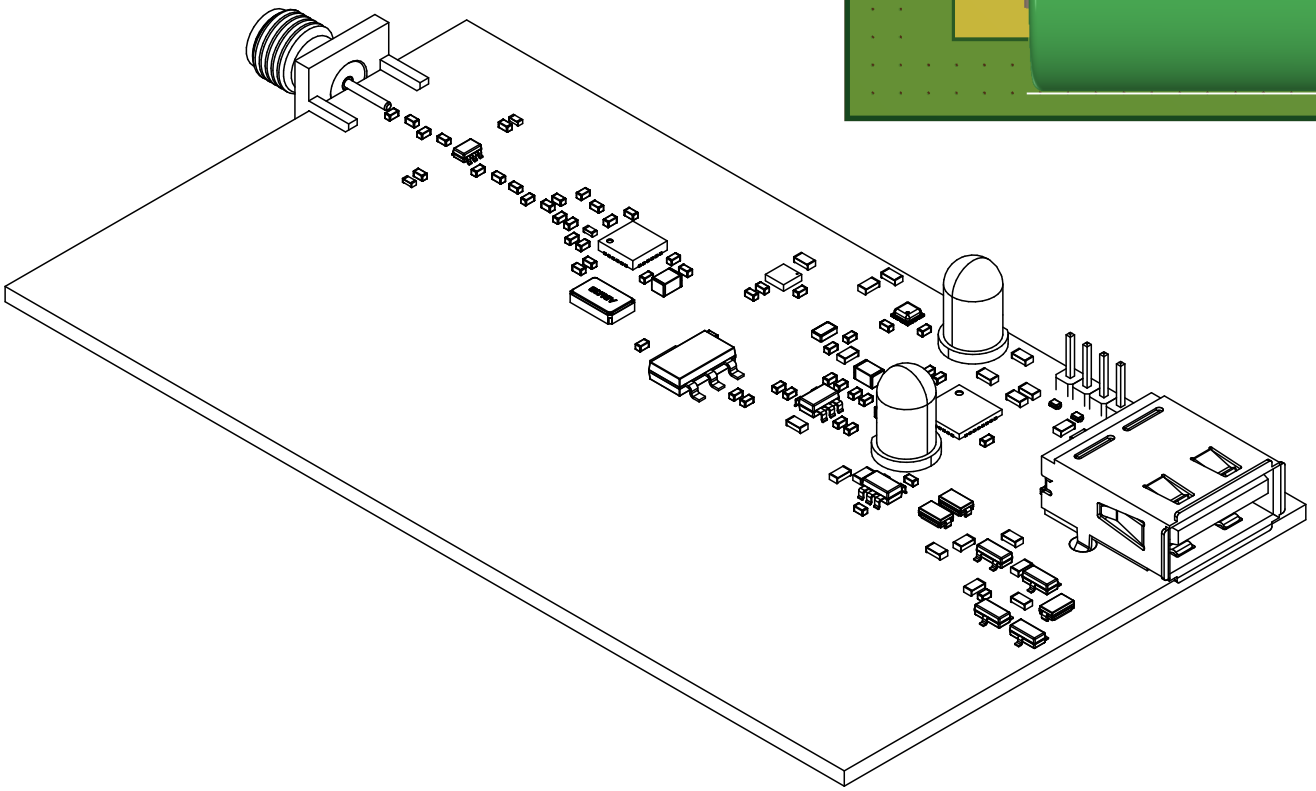
Widok 3D PCB oraz rzut izometryczny





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Wykonanie:	V1
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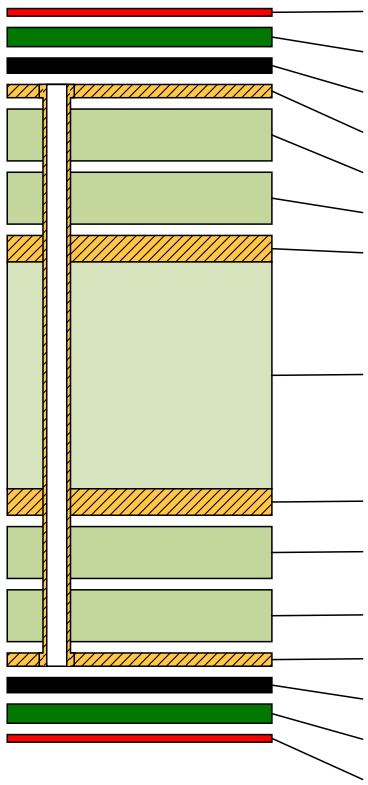
Stackup PCB

Layer Stack Legend



Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.03mm	SM-001	Solder Mask	GTS
PbSn	Top Surface Finish	0.02mm		Surface Finish	
CF-004	**L1 (Sig / PWR)**	**0.02mm**		**Signal**	**GTL**
Prepreg		*0.07mm*	*PP-005*	*Dielectric*	
Prepreg		*0.07mm*	*PP-005*	*Dielectric*	
CF-004	**L2 (GND)**	**0.04mm**		**Signal**	**G1**
Core		*1.20mm*	*Core-039*	*Dielectric*	
CF-004	**L3 (GND)**	**0.04mm**		**Signal**	**G2**
Prepreg		*0.07mm*	*PP-005*	*Dielectric*	
Prepreg		*0.07mm*	*PP-005*	*Dielectric*	
CF-004	**L4 (Sig / PWR)**	**0.02mm**		**Signal**	**GBL**
PbSn	Bottom Surface Finish	0.02mm		Surface Finish	
Surface Material	Bottom Solder	0.03mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 1.67mm

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